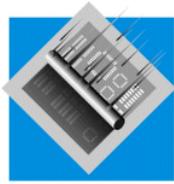


VIGON® UC 160

Water-based cleaning agent with high wetting ability for stencil underside wiping in printers



VIGON® UC 160 is a water-based cleaning agent specifically designed to remove solder paste from stencils in SMT printers. VIGON® UC 160 has an excellent wetting ability, which leads to an improved cleaning performance and thereby reduces smearing on the stencil underside significantly. This in turn prevents solder paste bridging on boards and ensures good and reliable printing results. VIGON® UC 160 is also an ideal replacement for Isopropanol due excellent health and safety characteristics, such as no flashpoint and a low VOC value.

Isopropanol due excellent health and safety characteristics, such as no flashpoint and a low VOC value.

Areas of application: Stencil and underside wipe cleaning		Additional product information :
Solder pastes (unsoldered)	++	Technical Information sheet 3: Overview regarding material compatibility

++ highly recommended, best results + recommended 0 possible - not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China
Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other cleaners:

- VIGON® UC 160 effectively removes the latest lead-free & lead-based solder pastes from stencils in underside wiping even out of fine pitch apertures. The cleaner is specifically suitable for print after wait.
- Provides excellent wetting ability on stencils and therefore increased cleaning performance, which significantly reduces smearing on the stencil underside. Thus bridging of solder paste on the boards can be avoided.
- Good delineation stability further ensures reduced solder balling.
- High operational safety and ideal replacement for Isopropanol due to excellent health and safety characteristics, no flash point, low VOC levels.
- VIGON® UC 160 has low odor.

Please refer to the material compatibility list (Technical Information 3) before using with plastic parts in the printer.

Process Steps	1. Wet	2. Vacuum	3. Dry
SMT Printer	VIGON® UC 160	Paper	Paper

Technical Data		
VIGON® UC 160 is available as ready-to-use solution Please note that the information below represents VIGON® UC 160 as a ready-to-use mixture.		
Density	(g/ccm) at 20°C/68°F	1.00
Surface tension	(mN/m) at 25°C/77°F	43.1
Boiling range	°C/°F	100 - 190 / 212 - 374
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	Approx. 21.0
Cleaning temperature	°C/°F	Room Temperature
Application concentration	Ready-to-use	Pure
HMIS Rating	Health-Flammability-Reactivity	0 - 0 - 0

PRODUCT FEATURES



MPC® Technology



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Environmental, health and safety regulations

- VIGON® UC 160 is water-based and biodegradable.
- The cleaning agent is formulated free of halogenated compounds.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- VIGON® UC 160 is available in 1l bottles, 5l or 25l containers and 200l drums.
- This product is a non-hazardous material.
- Store VIGON® UC 160 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For stencil underside wipe cleaning in printers without vacuum drying, we recommend the solvent-based cleaning agent ZESTRON® SW.



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